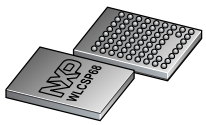

SOT1975-1

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

25 May 2018 **Package information**

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP68
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	16-5-2018
Manufacturer package code	98ASA01214D

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		-	3.78	-	mm
package width		-	3.06	-	mm
seated height		-	0.49	-	mm
nominal pitch		-	0.35	-	mm
actual quantity of termination		-	68	-	A/A

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

2. Package outline

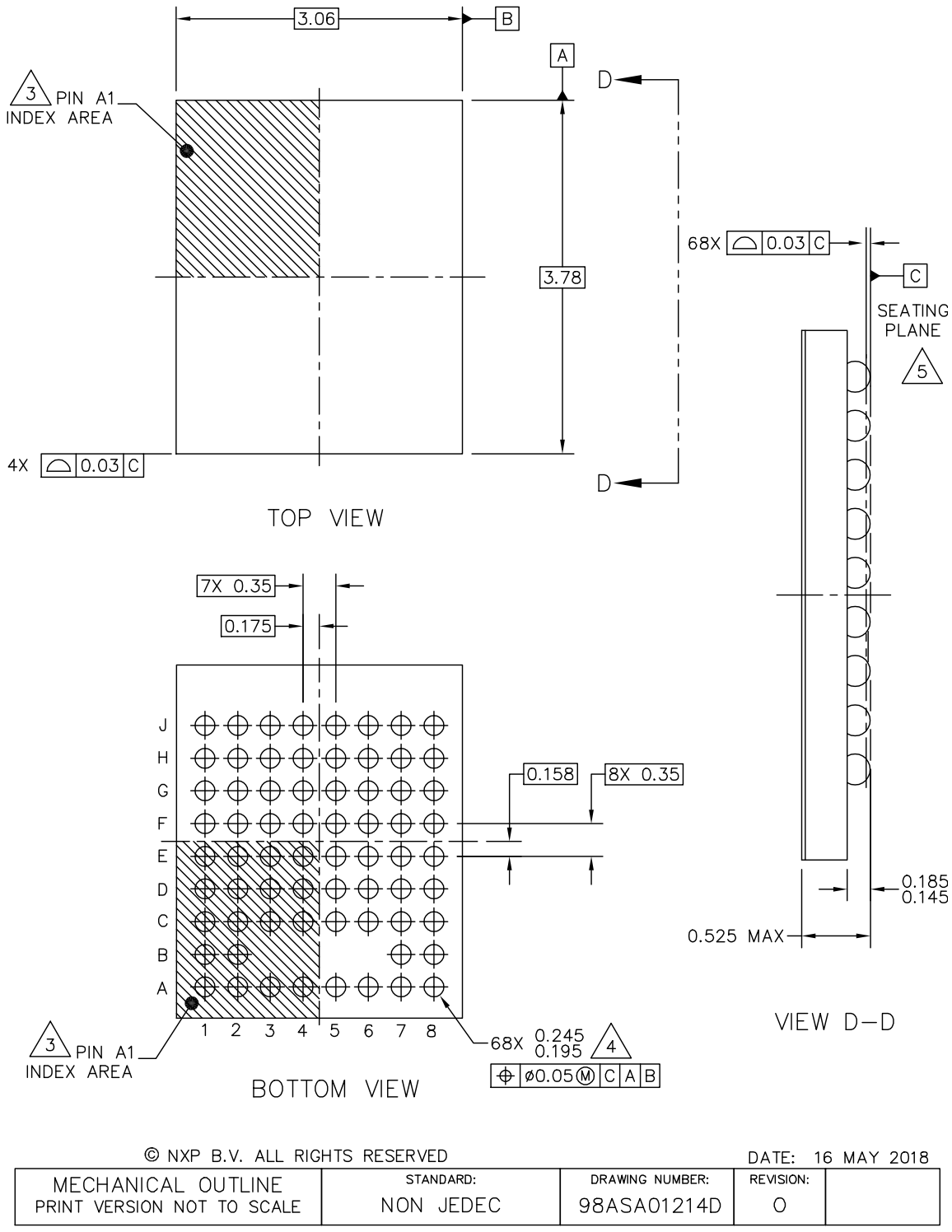

Fig. 1. Package outline SOT1975-1

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

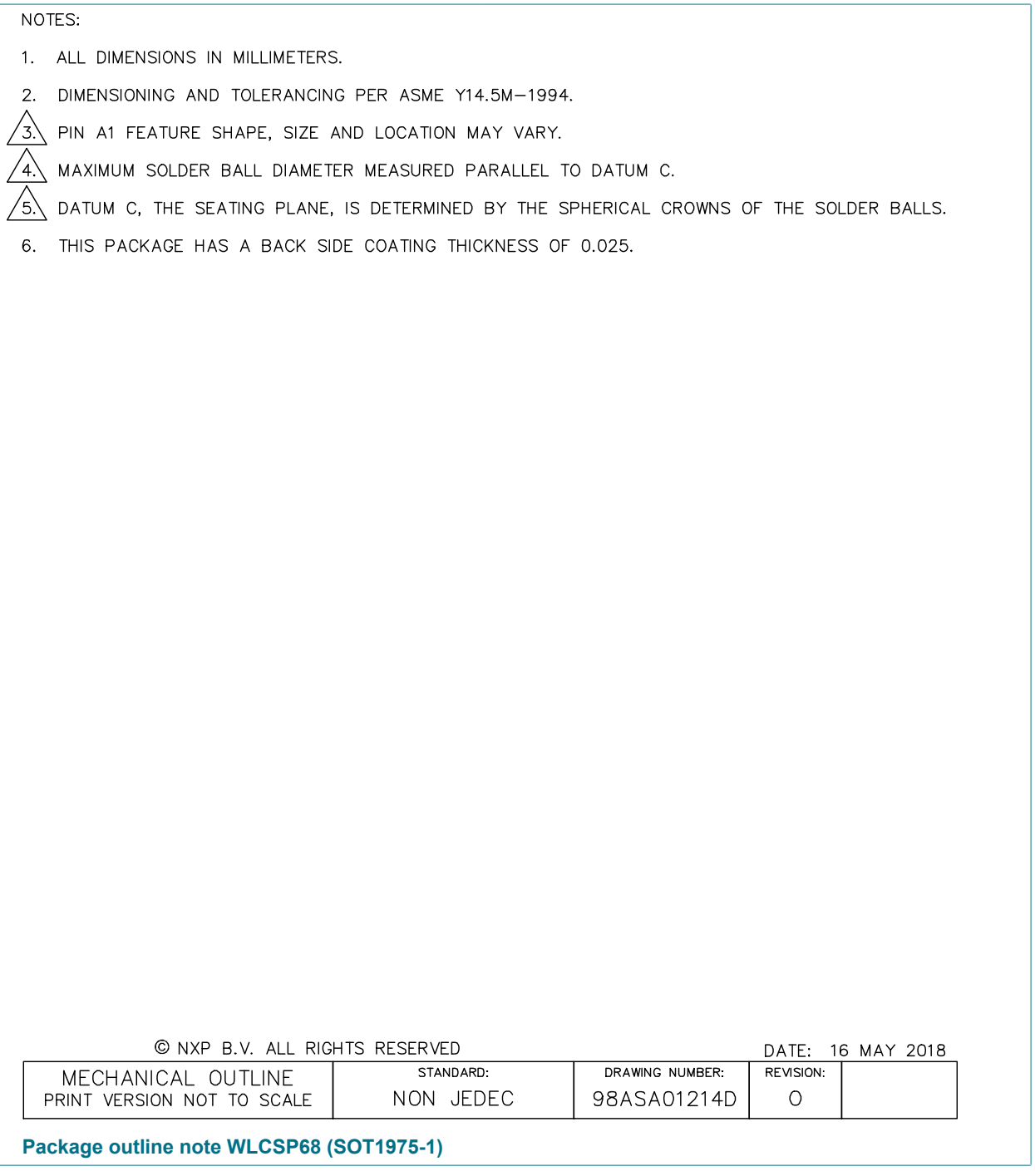

Fig. 2. Package outline note WLCSP68 (SOT1975-1)

3. Soldering

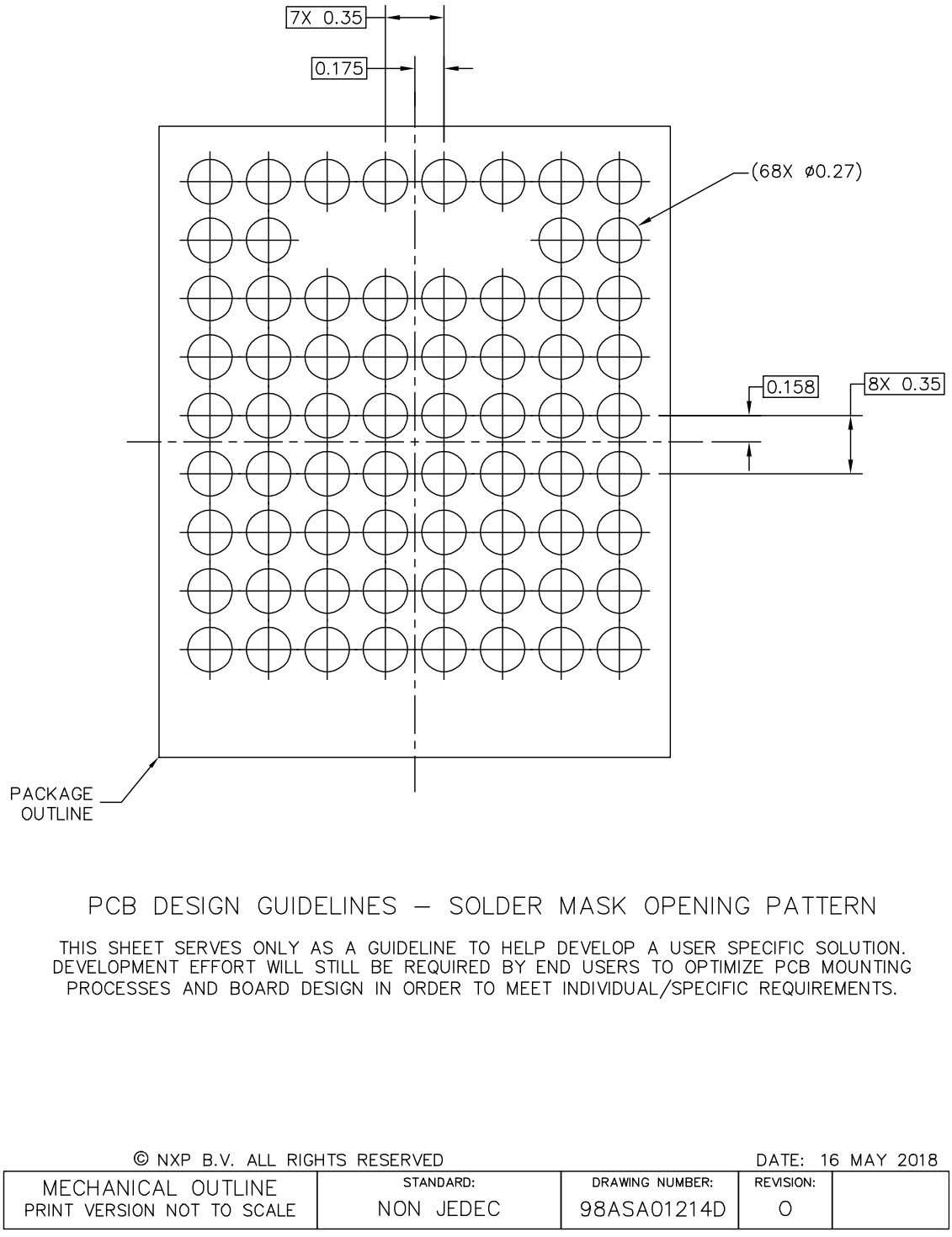

Fig. 3. Reflow soldering footprint for SOT1975-1

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

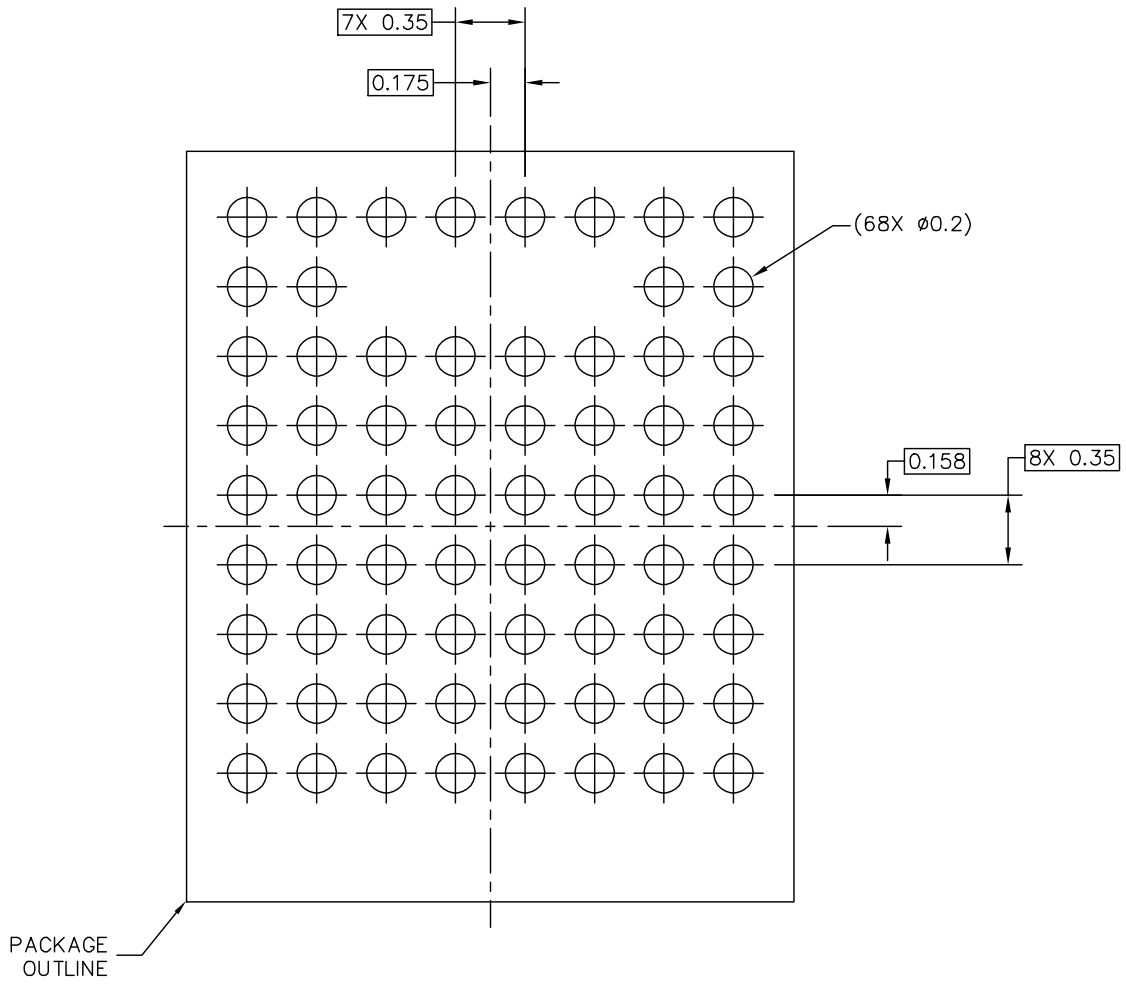

Fig. 4. Reflow soldering footprint part2 for WLCSP68 (SOT1975-1)

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

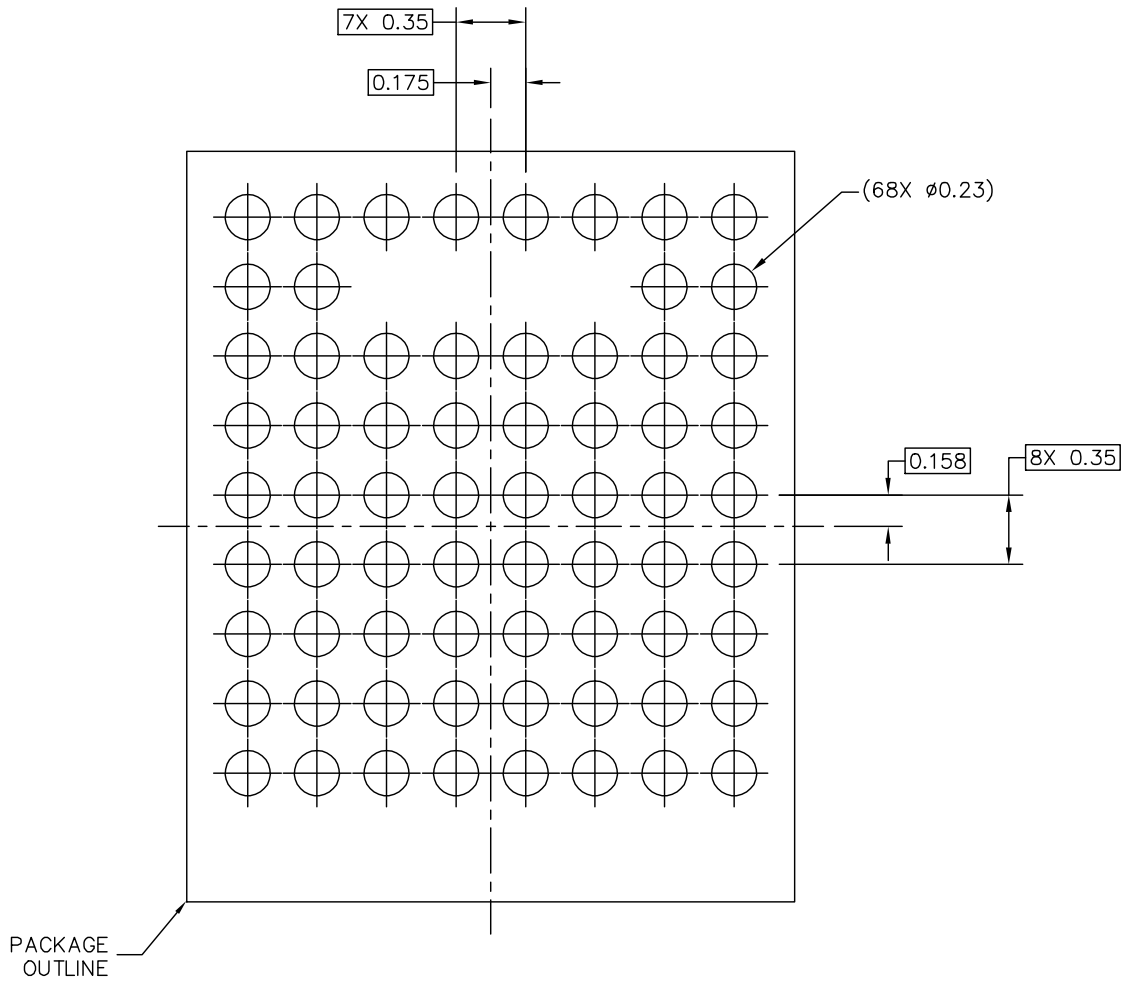

Fig. 5. Reflow soldering footprint part3 for WLCSP68 (SOT1975-1)

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5. Contents

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Date of release: 25 May 2018